





3.38	198	@adice="19991215" and (438.890).ccls.	US:PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TOB	OR	ON	2007/08/14 10:25
3.39	198	@adice="19991215" and (438.93).ccls.	US:PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TOB	OR	ON	2007/08/14 10:25
3.40	104	@adice="19991215" and (438.759).ccls.	US:PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TOB	OR	ON	2007/08/14 10:25
3.41	70	@adice="19991215" and (438.411).ccls.	US:PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TOB	OR	ON	2007/08/14 10:25
3.42	187	@adice="19991215" and (438.461).ccls.	US:PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TOB	OR	ON	2007/08/14 10:25
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